

ON Semiconductor 10/15/2019

Base Part		NC7SZ18	HF	Pb-free
Orderable Part		NC7SZ18L6X	Total weight (mg)	1.666
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight
Die	0.121	Silicon (Si)	7440-21-3	100
Die Attach	0.015	Phenolic Resin-2	54208-63-8	33.33333333
		Ortho Cresol Novolac Resin	29690-82-2	66.66666667
Mold Compound-Black	0.927	Ortho Cresol Novolac Resin	29690-82-2	14.99460626
		Carbon Black (C)	1333-86-4	0.53937433
		Fused Silica (SiO2)	60676-86-0	81.98489752
		Magnesium Hydroxide (Mg(OH)2)	1309-42-8	2.4811219
Plating	0.025	Nickel (Ni)	7440-02-0	24
		Gold (Au)	7440-57-5	76
Substrate	0.547	Bismaleimide	13676-54-5	42.77879342
		Cyanic acid (1-methylethylidene)di-4,1-phenylene ester homopolymer	25722-66-1	31.99268739
		Aluminum Trioxide (Al2O3)	1344-28-1	2.55941499
		Nickel (Ni)	7440-02-0	2.55941499
		Gold (Au)	7440-57-5	0.54844607
		Copper (Cu)	7440-50-8	19.56124314
Wire Bond - Au	0.031	Gold (Au)	7440-57-5	100

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:

<http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF>